

**Amendment history of SSD1351 Specification**

<b>Revision</b>	<b>Description of any change</b>	<b>Issued</b>	<b>Effective</b>
0.10 C6FA1 30-May-08	1 <sup>st</sup> draft  Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Jimmy Chiu Quality & Manufacturing-Daniel Ho Test Engineering - Warren Wong	Johnkid Lo	10-Jun-08
1.0 C6FA2 11-Dec-08	<ol style="list-style-type: none"> <li>1. Change to Advance information</li> <li>2. Add amendment history</li> <li>3. Add U1 , U2, U3 dwg into appendix</li> <li>4. Revise die thickness tolerance from <math>\pm 25\mu\text{m}</math> to <math>\pm 15\mu\text{m}</math> on Fig 5-1 &amp; section 3</li> <li>5. Remove “The typical regulated <math>V_{DD}</math> is about 2.5V” in section 8.10 &amp; figure 14-1</li> <li>6. Revise table 12-1 DC characteristic</li> <li>7. Revise table 13-1,13-2,13-3,13-4,13-5 (<math>V_{CI}</math> range) AC characteristic</li> <li>8. Remove <math>V_{DD}</math> range in Section 12 &amp; 13</li> <li>9. Revise command table for A0h, 96h, B2h</li> <li>10. Revise <math>V_{CC}</math> voltage range from 10V-20V to 10V to 18V               <ol style="list-style-type: none"> <li>i. Section 2 Feature list</li> <li>ii. Section 8.6 SEG/COM Driving block</li> <li>iii. Section 11 Maximum rating</li> <li>iv. Section 12 DC characteristic</li> <li>v. Section 14 Application example</li> </ol> </li> <li>11. Revise typo in Table 6-1: SSD1351UR1 Pin Assignment Table</li> </ol> Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo Quality & Manufacturing-Kenneth Ho Test Engineering - Stephen Leung	Ada Ng	12-Dec-08
1.1 C6FA2 19-Feb-09	<ol style="list-style-type: none"> <li>1 Revised Section 8.1 MCU interface               <ol style="list-style-type: none"> <li>1.1 Revise Figure 8-2 &amp; 8-3 : from D[7:0] to D[17:0]</li> <li>1.2 Revise Section 8.1.3 &amp; 8.1.4, Figure 8-5, Figure 8-6, Figure 13-3, Figure 13-4 : From “RW acts as SCLK, D0 acts as SDIN” to “D0 acts as SCLK, D1 acts as SDIN”</li> </ol> </li> <li>2 Revised Note (5) of Figures 8-13 &amp; 8-14 on P.30</li> <li>3 Add SSD1351U4R1 in appendix.</li> </ol> Approver list: Product Marketing- Raymond Ho Design Engineering- Kenneth Lee Product Engineering- Johnkid Lo Quality & Manufacturing- Daniel Ho Test Engineering - Stephen Leung	Ada Ng	19-Feb-09

Revision	Description of any change	Issued	Effective
1.2 C6FA2 C6FA3 27-Aug-09	<ol style="list-style-type: none"> <li>1 Change “Gold Bump Die” to “COG” for SSD1351Z in Table 3-1 Ordering information</li> <li>2 Revise typo in Figure 5 1: SSD1351Z Die Drawing ( position of L, T alignment mark)</li> <li>3 Revise pin description of VSL pin</li> <li>4 Revise typo in P.45 : 10.1.9 Set Function selection (ABh)</li> <li>5 Add Note 2 in application example Fig 14-1.</li> <li>6 Add SSD1351U5R1 in appendix. V (date back)</li> <li>7 Add Command B2h into appendix VI</li> </ol> <p>Approver list:            Product Marketing- Raymond Ho            Design Engineering- Kenneth Lee            Product Engineering- Johnkid Lo            Quality &amp; Manufacturing- Daniel Ho            Test Engineering - PL Che</p>	Ada Ng	31-Aug-09
1.3 C6FA2 C6FA3 21-Oct-09	<ol style="list-style-type: none"> <li>1 Added +/- 0.05mm tolerance for Die Size (after sawing) in Section 5 – P.9</li> <li>2 Added command C1h in the description of command FDh – P.37</li> <li>3 Revised typo error on the description of command C1h – P.46</li> <li>4 Updated the <math>I_{SLP\ VCI}</math> sleep mode current section of Table 12-1 (Max = 50uA when internal <math>V_{DD}</math> is enabled) – P.49</li> <li>5 Revised disclaimer</li> <li>6 Date back the edition of Appendix 1.3 (for command B2h)</li> </ol> <p>Approver list:            Marketing – Raymond Ho            Design Engineering- Kenneth Lee            Product Engineering- Johnkid Lo            PQA – Daniel Ho            Test Engineering – Stephen Leung</p>	Ada Ng	28-Oct-09

**SSD1351**

*Advance Information*

**128 RGB x 128 Dot Matrix**  
**OLED/PLED Segment/Common Driver with Controller**

This document contains information on a new product. Specifications and information herein are subject to change without notice.

<http://www.solomon-systech.com>

**SSD1351**

Rev 1.3

P 1/58

Oct 2009

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**Appendix: IC Revision history of SSD1351 Specification**

<b>Version</b>	<b>Change Items</b>	<b>Effective Date</b>
0.10	1. 1 <sup>st</sup> release	10-Jun-08
1.0	<ol style="list-style-type: none"> <li>1. Change to Advance Info</li> <li>2. Revise die thickness tolerance from <math>\pm 25\mu\text{m}</math> to <math>\pm 15\mu\text{m}</math></li> <li>3. Revise table 12-1 DC characteristic</li> <li>4. Revise tables 13 AC characteristic</li> <li>5. Revise command table</li> <li>6. Revise <math>V_{CC}</math> voltage range</li> </ol>	12-Dec-08
1.1	1. Revised section 8.1 MCU interface	19-Feb-09
1.2	<ol style="list-style-type: none"> <li>1 Change “Gold Bump Die” to “COG” for SSD1351Z in Table 3-1 Ordering information</li> <li>2 Revise typo in Figure 5 1: SSD1351Z Die Drawing ( position of L, T alignment mark)</li> <li>3 Revise typo in P.45 : 10.1.9 Set Function selection (ABh)</li> <li>4 Add Note 2 in application example Fig 14-1</li> </ol>	31-Aug-09
1.3	<ol style="list-style-type: none"> <li>1 Added +/- 0.05mm tolerance for Die Size (after sawing) in Section 5 – P.9</li> <li>2 Added command C1h in the description of command FDh – P.37</li> <li>3 Revised typo error on the description of command C1h – P.46</li> <li>4 Updated the <math>I_{SLP_{VCI}}</math> sleep mode current section of Table 12-1 (Max = 50uA when internal <math>V_{DD}</math> is enabled) – P.49</li> <li>5 Revised declaimer</li> </ol>	28-Oct-09





























































































































